

## Super FAP-E<sup>3S</sup> Low Qg series

### N-Channel enhancement mode power MOSFET

#### ■Features

Low on-state resistance  
 Low switching loss  
 easy to use  
 (more controllable switching  $dV/dt$  by  $R_g$ )  
 The reliability trial conforms to AEC Q101.  
 100% avalanche tested

#### ■Applications

Automotive switching applications

#### ■Absolute Maximum Ratings at $T_c=25^\circ\text{C}$ (unless otherwise specified)

| Description                              | Symbol    | Characteristics | Unit              | Remarks              |
|------------------------------------------|-----------|-----------------|-------------------|----------------------|
| Drain-Source Voltage                     | $V_{DS}$  | 600             | V                 |                      |
|                                          | $V_{DSX}$ | 600             | V                 | $V_{GS}=-30\text{V}$ |
| Continuous Drain Current                 | $I_D$     | $\pm 31$        | A                 |                      |
| Pulsed Drain Current                     | $I_{DP}$  | $\pm 124$       | A                 |                      |
| Gate-Source Voltage                      | $V_{GS}$  | $\pm 30$        | V                 |                      |
| Non-Repetitive Maximum Avalanche current | $I_{AS}$  | 31              | A                 | Note*1               |
| Non-Repetitive Maximum Avalanche Energy  | $E_{AS}$  | 631             | mJ                | Note*2               |
| Peak Diode Recovery $dV/dt$              | $dV/dt$   | 4.7             | kV/ $\mu\text{s}$ | Note*3               |
| Peak Diode Recovery $di/dt$              | $-di/dt$  | 100             | A/ $\mu\text{s}$  | Note*4               |
| Maximum Power Dissipation                | $P_D$     | 495             | W                 |                      |
| Operating and Storage Temperature range  | $T_{ch}$  | 150             | $^\circ\text{C}$  |                      |
|                                          | $T_{stg}$ | -55 to +150     | $^\circ\text{C}$  |                      |

Note\*1 :  $T_{ch} \leq 150^\circ\text{C}$ , See Fig.1 and Fig.2

Note\*2 : Starting  $T_{ch}=25^\circ\text{C}$ ,  $L=1200\mu\text{H}$ ,  $V_{CC}=60\text{V}$ ,  $R_G=50\Omega$ , See Fig.1 and Fig.2

$E_{AS}$  limited by maximum channel temperature and avalanche current.

See to Avalanche Energy graph of page 5

Note\*3 :  $IF \leq -ID$ ,  $-di/dt=100\text{A}/\mu\text{s}$ ,  $V_{CC} \leq BV_{DSS}$ ,  $T_{ch} \leq 150^\circ\text{C}$

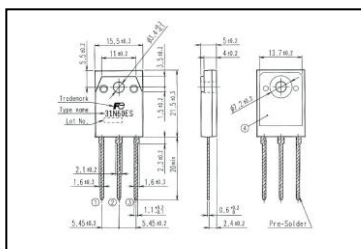
Note\*4 :  $IF \leq -ID$ ,  $dV/dt=4.7\text{kV}/\mu\text{s}$ ,  $V_{CC} \leq BV_{DSS}$ ,  $T_{ch} \leq 150^\circ\text{C}$

#### ■Electrical Characteristics at $T_c=25^\circ\text{C}$ (unless otherwise specified)

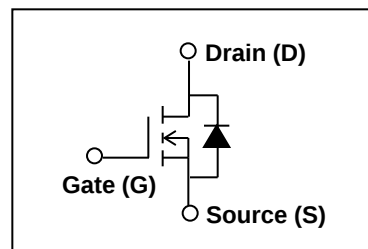
##### Static Ratings

| Description                      | Symbol       | Conditions                                                            | Min. | Typ. | Max. | Unit          |
|----------------------------------|--------------|-----------------------------------------------------------------------|------|------|------|---------------|
| Drain-Source Breakdown Voltage   | $BV_{DSS}$   | $I_D=1\text{mA}$<br>$V_{GS}=0\text{V}$                                | 600  | —    | —    | V             |
|                                  | $BV_{DSX}$   | $I_D=1\text{mA}$<br>$V_{GS}=-30\text{V}$                              | 600  | —    | —    | V             |
| Gate Threshold Voltage           | $V_{GS(th)}$ | $I_D=250\mu\text{A}$<br>$V_{DS}=V_{GS}$                               | 3.7  | 4.2  | 4.7  | V             |
| Zero Gate Voltage Drain current  | $I_{DSS}$    | $V_{DS}=600\text{V}$<br>$V_{GS}=0\text{V}$<br>$T_a=25^\circ\text{C}$  | —    | 0.7  | 10   | $\mu\text{A}$ |
|                                  |              | $V_{DS}=480\text{V}$<br>$V_{GS}=0\text{V}$<br>$T_a=125^\circ\text{C}$ | —    | 25   | 250  |               |
| Gate-Source Leakage current      | $I_{GSS}$    | $V_{GS}=30\text{V}$<br>$V_{DS}=0\text{V}$                             | —    | 10   | 100  | nA            |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $I_D=15.5\text{A}$<br>$V_{GS}=10\text{V}$                             | —    | 170  | 200  | m $\Omega$    |

#### ■Outline Drawings [mm]



#### ■Equivalent circuit schematic



## Dynamic Ratings

| Description                  | Symbol       | Conditions                                                                    | Min. | Typ. | Max. | Unit |
|------------------------------|--------------|-------------------------------------------------------------------------------|------|------|------|------|
| Forward Transconductance     | $g_{fs}$     | $I_D=15.5A$<br>$V_{DS}=25V$                                                   | 11   | —    | —    | S    |
| Input Capacitance            | $C_{iss}$    | $V_{DS}=25V$<br>$V_{GS}=0V$<br>$f=1MHz$                                       | —    | 4810 | —    | pF   |
| Output Capacitance           | $C_{oss}$    |                                                                               | —    | 535  | —    |      |
| Reverse Transfer Capacitance | $C_{rss}$    |                                                                               | —    | 32   | —    |      |
| Turn-On Time                 | $t_{d(on)}$  | $V_{CC}=300V, V_{GS}=10V$<br>$I_D=15.5A, R_G=10\Omega$<br>See Fig.3 and Fig.4 | —    | 55   | —    | ns   |
|                              | $t_r$        |                                                                               | —    | 80   | —    |      |
| Turn-Off Time                | $t_{d(off)}$ |                                                                               | —    | 130  | —    |      |
|                              | $t_f$        |                                                                               | —    | 30   | —    |      |
| Total Gate Charge            | $Q_G$        | $V_{DD}=300V, I_D=31A$<br>$V_{GS}=10V$<br>See Fig.5                           | —    | 125  | —    | nC   |
| Gate-Source Charge           | $Q_{GS}$     |                                                                               | —    | 45   | —    |      |
| Gate-Drain Charge            | $Q_{GD}$     |                                                                               | —    | 55   | —    |      |

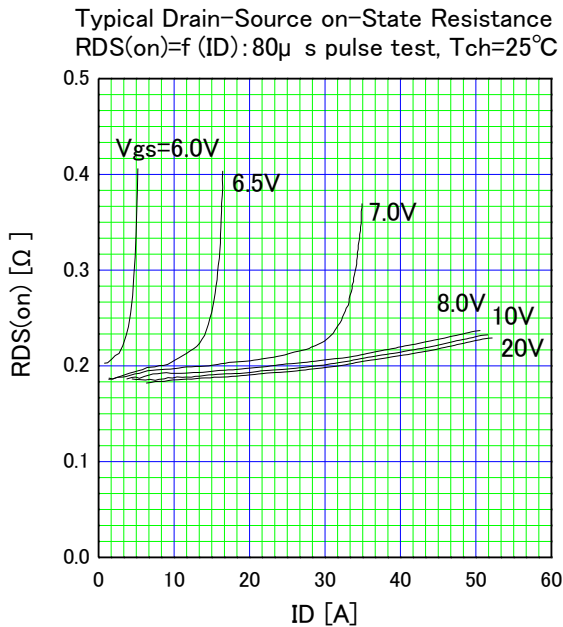
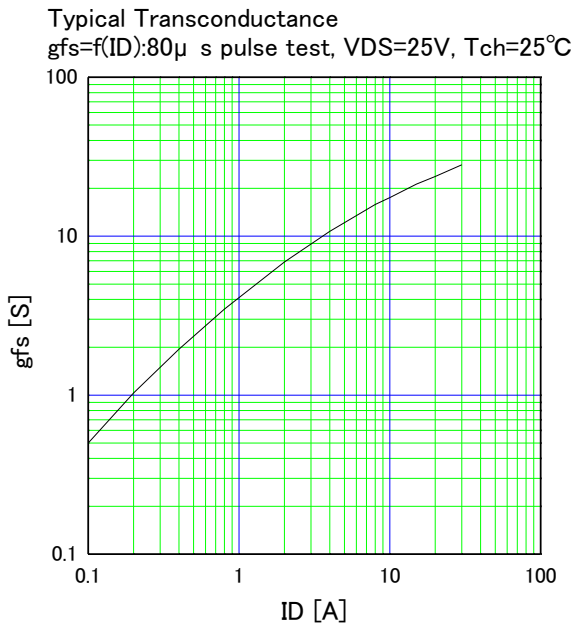
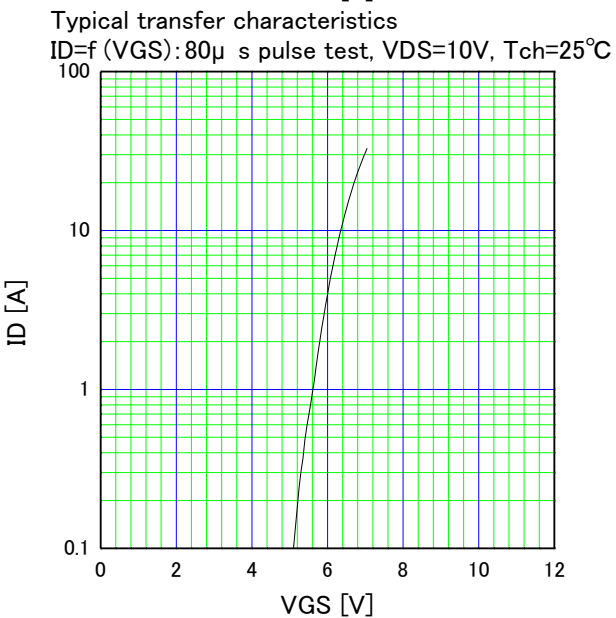
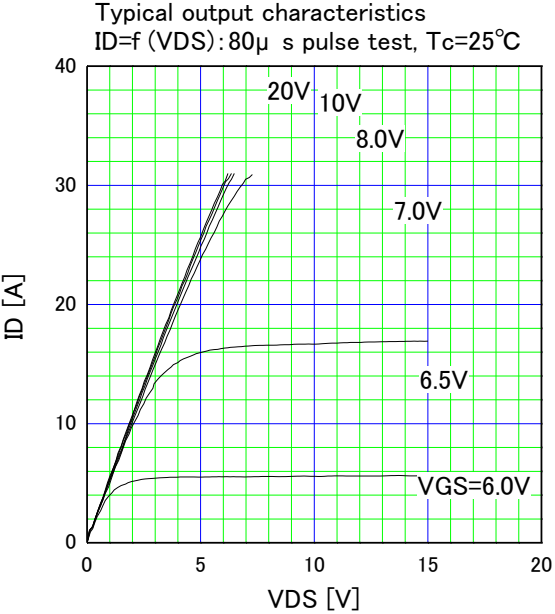
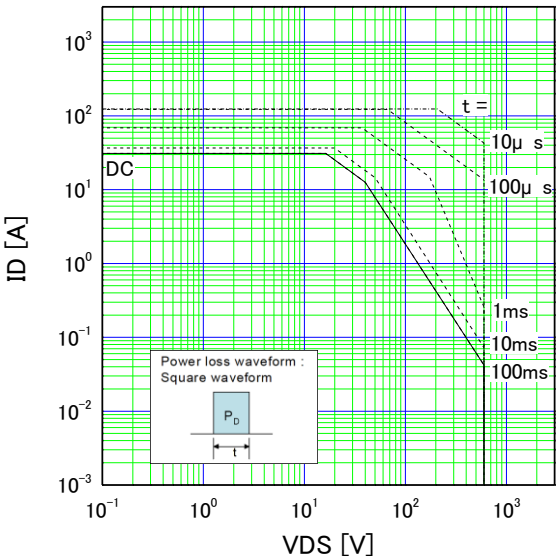
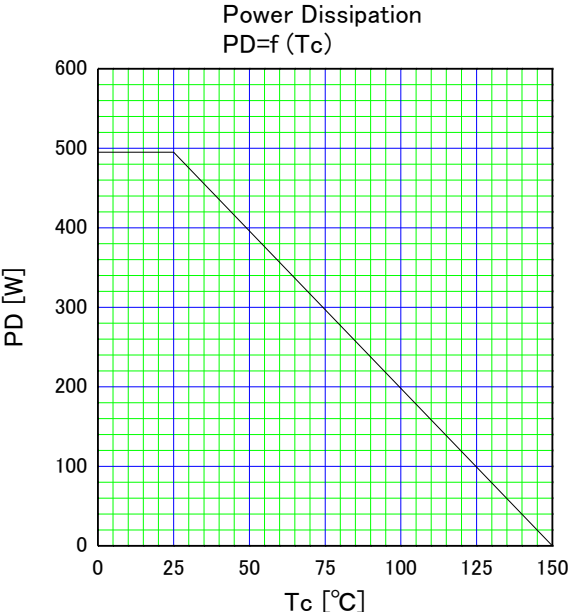
## Reverse Ratings

| Description               | Symbol   | Conditions                                                         | Min. | Typ. | Max. | Unit    |
|---------------------------|----------|--------------------------------------------------------------------|------|------|------|---------|
| Avalanche Capability      | $I_{AV}$ | $L=1200\mu H, T_{ch}=25^\circ C$<br>See Fig.1 and Fig.2            | 31   | —    | —    | A       |
| Diode Forward On- Voltage | $V_{SD}$ | $I_F=31A, V_{GS}=0V$<br>$T_{ch}=25^\circ C$                        | —    | 1.10 | 1.5  | V       |
| Reverse Recovery Time     | $t_{rr}$ | $I_F=31A, V_{GS}=0V$<br>$-di/dt=100A/\mu s$<br>$T_{ch}=25^\circ C$ | —    | 700  | —    | ns      |
| Reverse Recovery Charge   | $Q_{rr}$ |                                                                    | —    | 18   | —    | $\mu C$ |

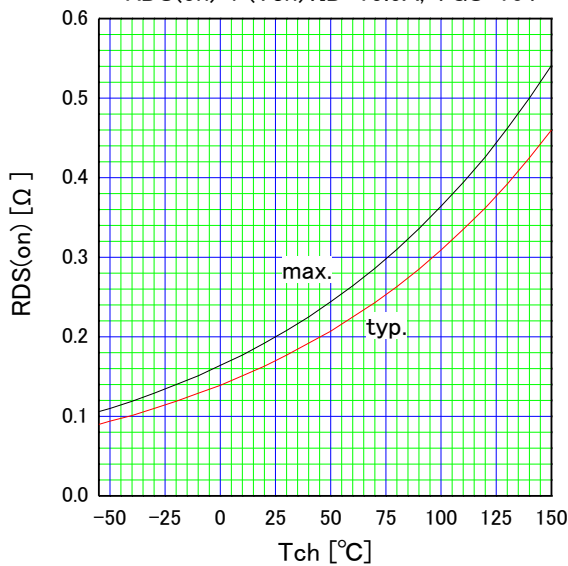
## ■ Thermal Characteristics

| Description       | Symbol         | Min. | Typ. | Max.  | Unit         |
|-------------------|----------------|------|------|-------|--------------|
| Cannel to Case    | $R_{th(ch-c)}$ | —    | —    | 0.252 | $^\circ C/W$ |
| Cannel to Ambient | $R_{th(ch-a)}$ | —    | —    | 50.0  | $^\circ C/W$ |

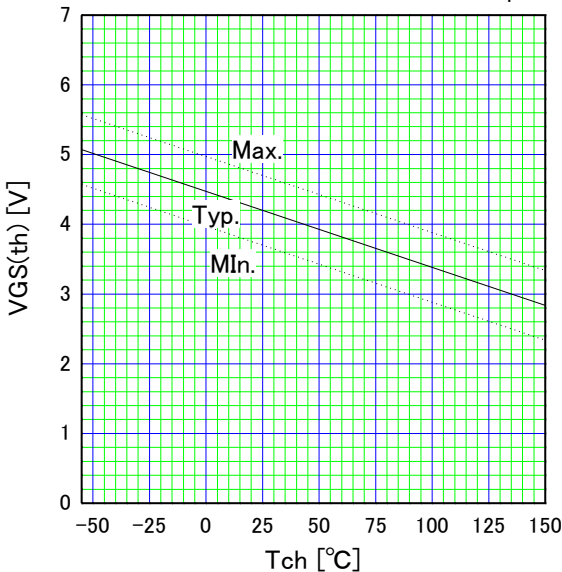
Safe operating area  
 $I_D=f(V_{DS})$ : Single pulse ( $D=0$ ),  $T_c=25^\circ\text{C}$



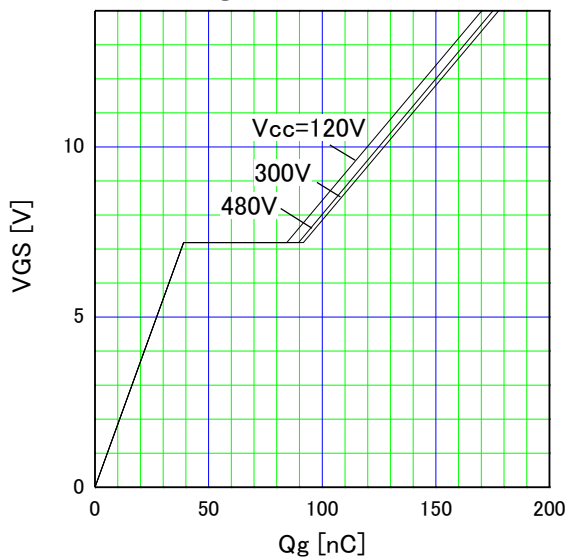
Drain-source on-state resistance  
 $R_{DS(on)}=f(T_{ch}):I_D=15.5A, V_{GS}=10V$



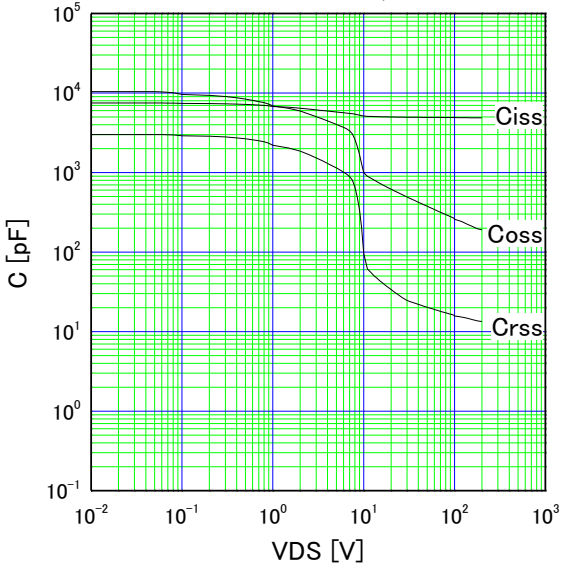
Gate Threshold Voltage vs.  $T_{ch}$   
 $V_{GS(th)}=f(T_{ch}):V_{DS}=V_{GS}, I_D=250\mu A$



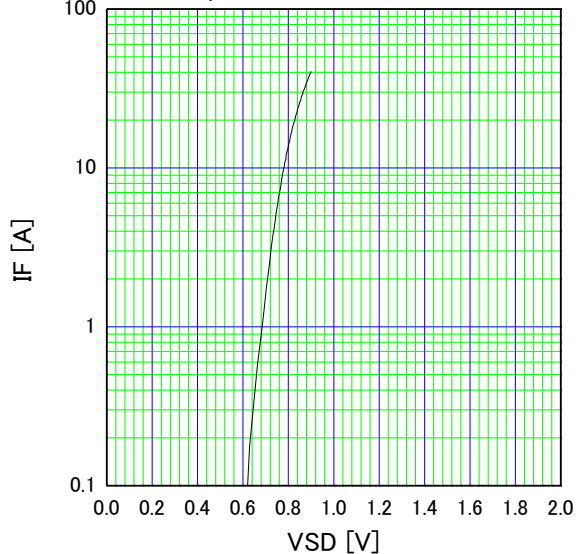
Typical Gate Charge Characteristics  
 $V_{GS}=f(Q_g):I_D=31A, T_{ch}=25^{\circ}C$



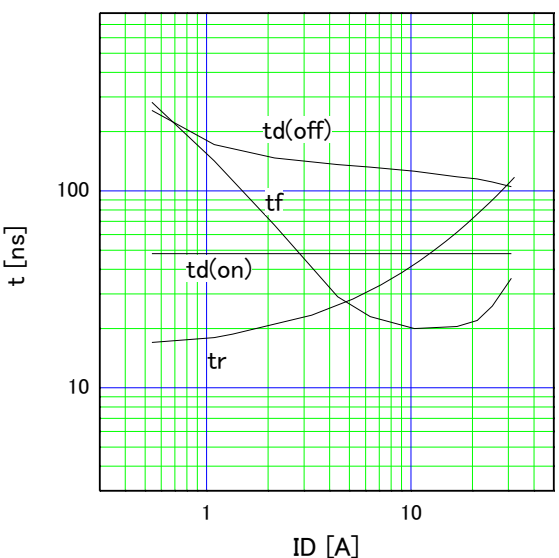
Typical capacitances  
 $C=f(V_{DS}):V_{GS}=0V, f=1MHz$



Typical Forward Characteristics of Reverse Diode  
 $I_F=f(V_{SD}):80\mu s$  pulse test,  $T_{ch}=25^{\circ}C$



Typical Switching Characteristics vs.  $I_D$   
 $t=f(I_D):V_{CC}=300V, V_{GS}=10V, R_G=10\Omega$



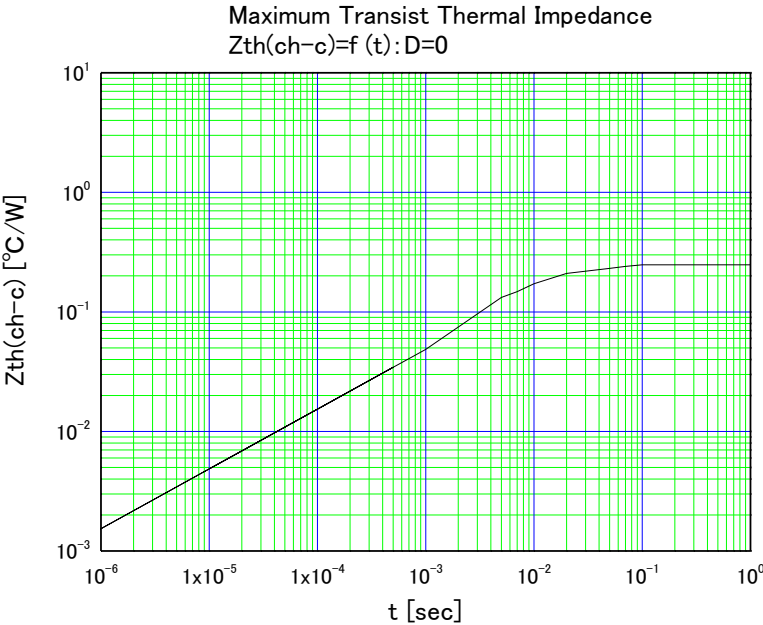
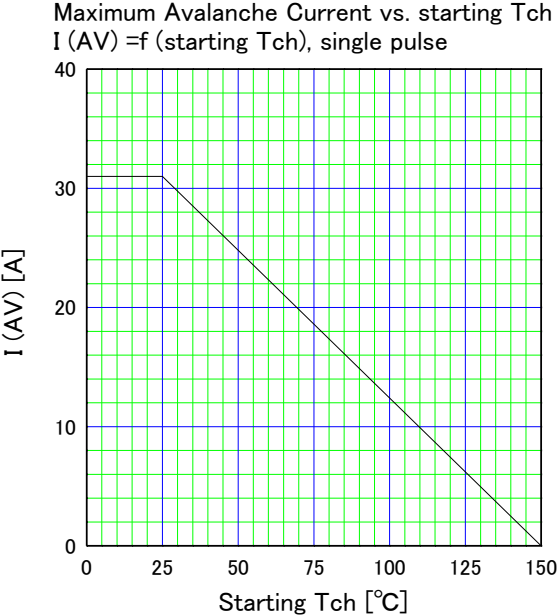
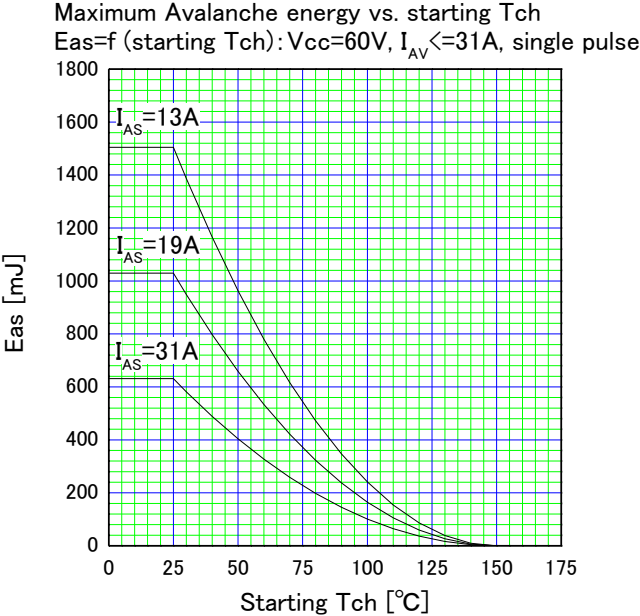


Fig.1 Avalanche Test circuit

Fig.2 Operating waveforms of Avalanche Test

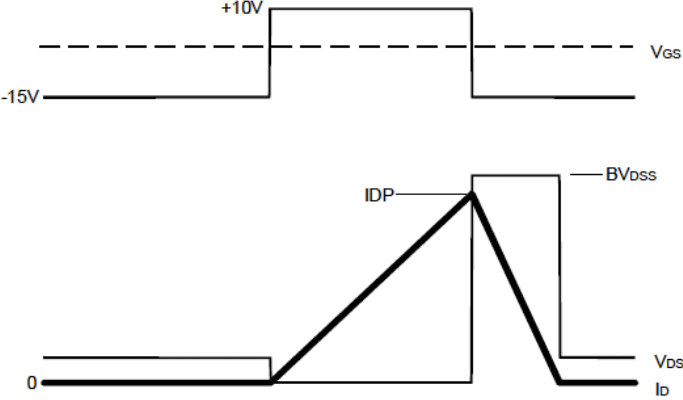
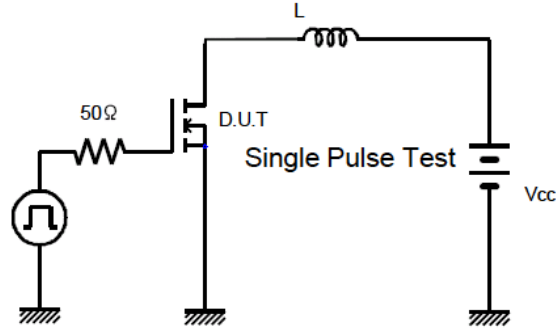


Fig.3 Switching Test circuit

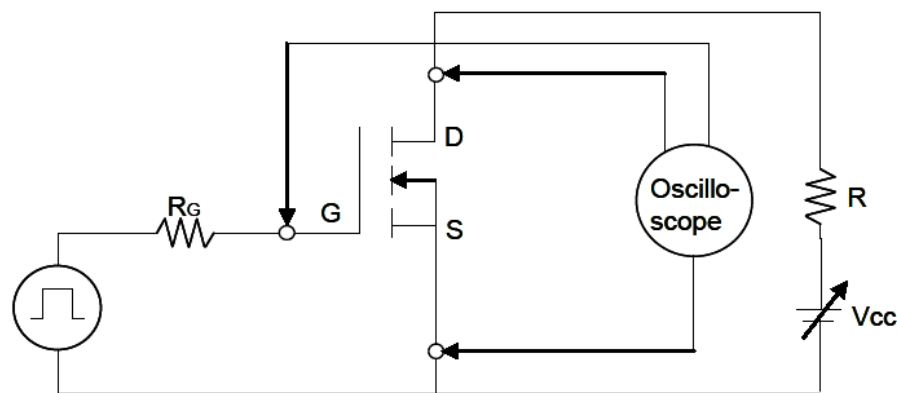


Fig.4 Operating waveform of Switching Test

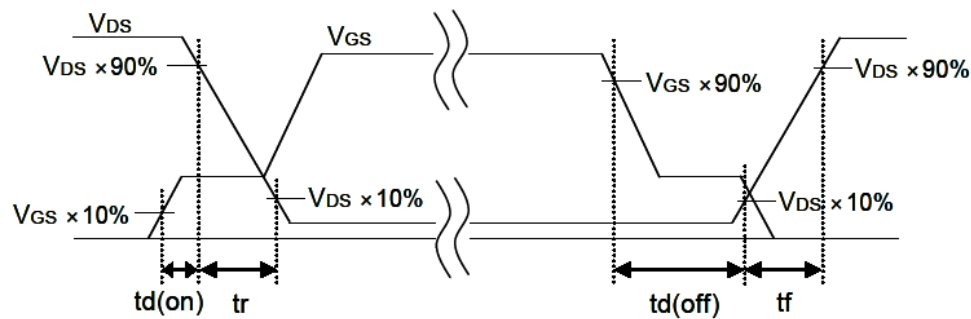


Fig.5 Operating waveform of Gate charge Test

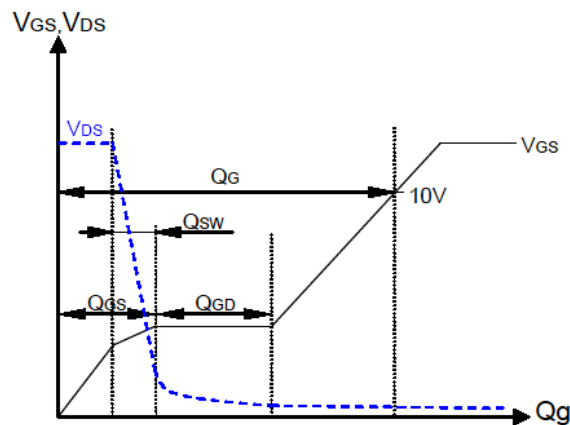
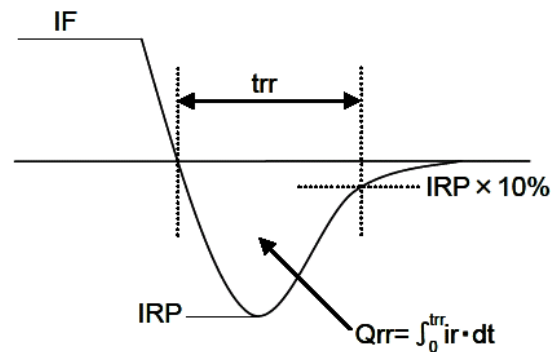


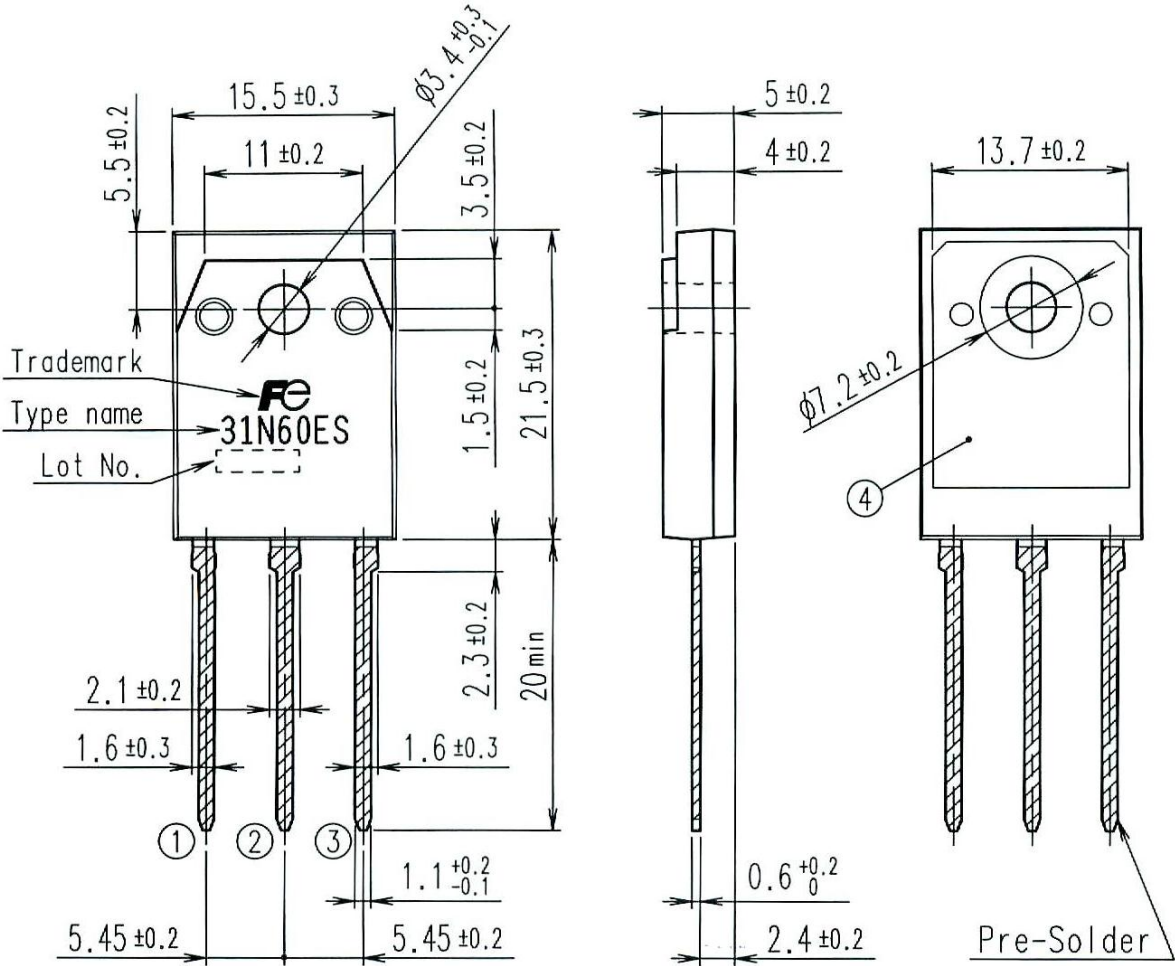
Fig.6 Operating waveform of Body diode Recovery Test



■ Out view

FUJI POWER MOSFET

TYPE : FMY31N60ES



CONNECTION

- ① GATE
- ② ④ DRAIN
- ③ SOURCE

JEDEC: TO-247

DIMENSIONS ARE IN MILLIMETERS.

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